

Transistors with Built-in Resistor DRC3143Y0L

DRC3143Y0L Silicon NPN epitaxial planar type

For digital circuits Complementary to DRA3143Y DRC9143Y in SSSMini3 type package

Features

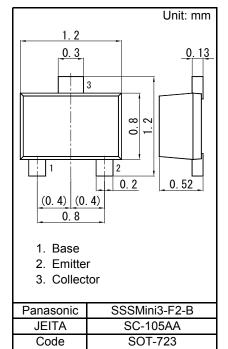
- · High forward current transfer ratio hFE
- Low collector-emitter saturation voltage Vce(sat)

Absolute Maximum Ratings Ta = 25 °C

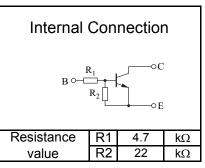
- Halogen-free / RoHS compliant
 (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: N7

Packaging

Embossed type (Thermo-compression sealing) : 10 000 pcs / reel (standard)



Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	VCBO	50	V
Collector-emitter voltage (Base open)	VCEO	50	V
Collector current	IC	100	mA
Total power dissipation	PT	100	mW
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C

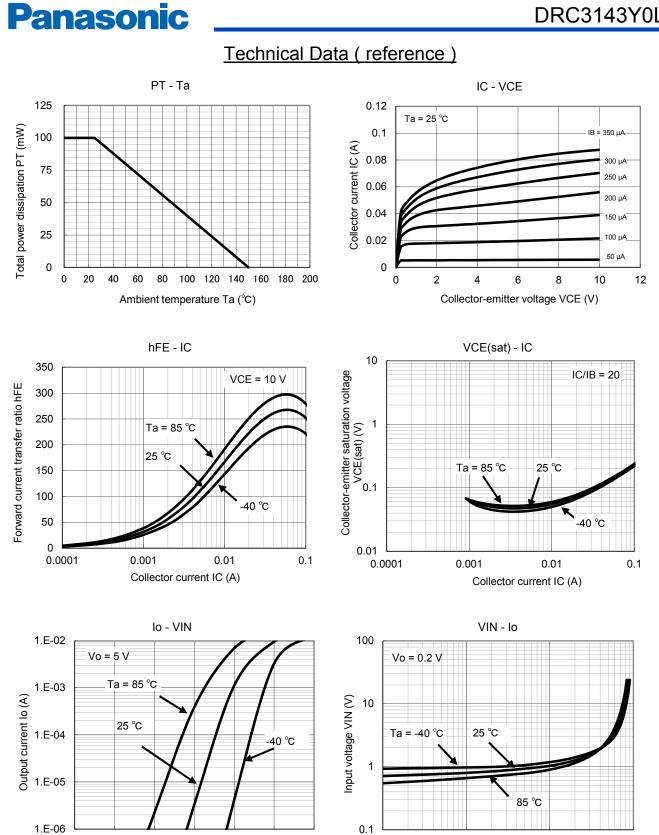


Electrical Characteristics Ta = $25 \circ C \pm 3 \circ C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	VCBO	IC = 10 μA, IE = 0	50			V
Collector-emitter voltage (Base open)	VCEO	IC = 2 mA, IB = 0	50			V
Collector-base cutoff current (Emitter open)	ICBO	VCB = 50 V, IE = 0			0.1	μA
Collector-emitter cutoff current (Base open)	ICEO	VCE = 50 V, IB = 0			0.5	μA
Emitter-base cutoff current (Collector open)	IEBO	VEB = 6 V, IC = 0			0.4	mA
Forward current transfer ratio	hFE	VCE = 10 V, IC = 5 mA	60		200	-
Collector-emitter saturation voltage	VCE(sat)	IC = 10 mA, IB = 0.5 mA			0.25	V
Input voltage	Vi(on)	VCE = 0.2 V, IC = 5 mA	1.2			V
	Vi(off)	VCE = 5 V, IC = 100 μA			0.5	V
Input resistance	R1		-30%	4.7	+30%	kΩ
Resistance ratio	R1/R2		0.17	0.21	0.27	-

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

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0.1

0

0.2

0.4

0.6

Input voltage VIN (V)

0.8

1

1.2

0.0001

0.001

0.01

Output current Io (A)



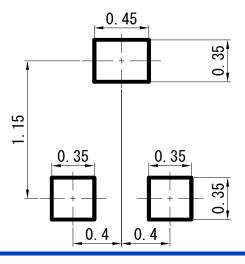
SSSMini3-F2-B

Transistors with Built-in Resistor DRC3143Y0L

Unit: mm

1.20 ± 0.05 0.13+0.05 0<u>. 30^{+0.05}</u> 3 0.80 ± 0.05 1. 20±0. 05 أى 2 1 0. 20+0. 05 0.20 ± 0.05 (0.4) (0.4) 0.80 ± 0.05 (5°) 27) 52 ± 0.03 ġ o' 0 to 0.05

Land Pattern (Reference) (Unit: mm)



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